

Title (en)

METHOD FOR MANUFACTURING A SMARTCARD MODULE AND SMARTCARD MODULE OBTAINED USING THIS METHOD

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES CHIPKARTENMODULS UND MITHILFE DIESES VERFAHRENS ERHALTENES CHIPKARTENMODUL

Title (fr)

PROCÉDÉ DE FABRICATION D'UN MODULE DE CARTE À PUCE ET MODULE DE CARTE À PUCE OBTENU PAR LEDIT PROCÉDÉ

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Application

**EP 22733905 A 20220530**

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Abstract (en)

[origin: WO2022258420A1] The invention relates to a method for manufacturing a smartcard module wherein an electronic component (20) is mounted on an upper face of a metal foil (10) and then covered with a first layer of dielectric material (30). Openings are made in the first layer of hardened dielectric material (30) and then everything is covered with a conducting layer (50) that fills the openings. The metal foil (10) and the conducting layer (50) are etched so as to create patterns of conductors. The invention also relates to a smartcard module in which an integrated circuit (20) is placed between a first (10) and a second (50) metallic layer inside a layer of dielectric material (30). The invention also relates to the smartcard module thus obtained.

IPC 8 full level

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